



## Cleaning medium for manual flux removal



VIGON<sup>®</sup> EFM is a precision cleaning agent designed to remove flux residues from electronic assemblies in manual applications. This product can also be used in explosion-proof spray-in-air equipment. VIGON<sup>®</sup> EFM is a mixture of halogen-free organic solvents. It dries fast and residue-free. VIGON<sup>®</sup> EFM is non-corrosive and compatible with most polymers.

Areas of application: PCB's		Additional product information :
Resin-based flux residues*	++	
Low solid flux residues*	0	<b>Technical Information sheet 3</b> : Overview regarding material compatibility
Water soluble flux residues*	-	
++ highly recommended, best results	+ recommended	0 possible - not recommended

\* Valid for all standard, lead-free and eutectic solder pastes

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



## Advantages compared to other cleaners:

- VIGON<sup>®</sup> EFM is especially suitable for the removal of resin-based flux residues.
- This product dries very fast and residue-free.
- VIGON<sup>®</sup> EFM is easy-to-use.
- It can be used for both manual and automatic cleaning in explosion-proof equipment.
- Very suitable as a cleaning and rinsing agent.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.





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Process Steps	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air	VIGON <sup>®</sup> EFM	VIGON <sup>®</sup> EFM	Compressed air or open air evaporation
Manual cleaning	VIGON <sup>®</sup> EFM	VIGON <sup>®</sup> EFM	Compressed air or open air evaporation

Technical Data				
Density	(g/ccm) at 20°C/68°C	0.72		
Surface tension	(mN/m) at 25°C/77°F	18.6		
Boiling range	°C/°F	78 - 120 / 172 - 248		
Flash point	°C/°F	-12 / 10		
pH-value	10g/l H <sub>2</sub> O	Neutral		
Vapor pressure	(mbar) at 20°C/68°F	Approx. 77		
Solubility in water		Not Soluble		
Cleaning temperature		Ambient Temperature		
Application concentration	Ready-to-use	Readymix		
HMIS Rating	Health-Flammability-Reactivity	1 - 4 - 0		

## **PRODUCT FEATURES**

**Availability/Storage:** 

5°C - 30°C / 41- 86°F.



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Extensively tested and suitable for cleaning of lead-free solder pastes

**Environmental, health and safety regulations:** 

It is a highly flammable cleaning medium.

VIGON<sup>®</sup> EFM is biodegradable.

manual removal of flux residues.

**Alternative product recommendation:** 

100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

Refer to the MSDS for specific handling precautions and instructions.

It is also available in 11 bottles, 251 or 551 containers and 2001 drums.

Store VIGON<sup>®</sup> EFM in the original container at a temperature between

The product has a minimum shelf life of 5 years in factory sealed containers.



VIGON® EFM is available as an easy-to-use aerosol can with detachable brush for the

For the manual removal of SMT adhesive we recommend ZESTRON® HC.

Product is free of any critical substances according to SIN & SVHC lists

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